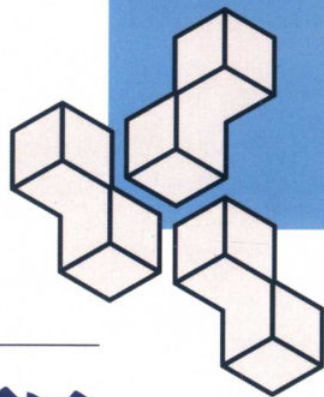


高等学校专业英语教材



电子信息工程

专业英语教程 (第5版)

◎ 任治刚 编著



中国工信出版集团



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高等学校专业英语教材

电子信息工程专业英语教程

(第5版)

Technical English Course for
Electronic Information Engineering
(Fifth Edition)

任治刚 编著

贵州师范学院内部使用

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内 容 简 介

本书的主要目的是使读者掌握电子信息工程专业英语术语及用法,培养和提高读者阅读和翻译专业英语文献资料的能力。本书由10个主题单元组成,涵盖了电子信息领域的主要技术分支。主要内容包括电子器件、电子电路、电子系统组件、电子系统、现代数字设计、数字信号处理、语音和音频、图像和视频、嵌入式应用、电子仪器与测量等。每个主题单元由3篇课文、3篇阅读材料、课文词汇、课文注释和练习组成。每篇课文均有参考译文,书后附有练习参考答案、科技英语语音手册和词汇手册;全书配有电子教案、视频材料等教辅资源,通过华信教育资源网 www.hxedu.com.cn 免费提供给授课教师参考。

本书可作为电子信息工程专业的专业英语教材,也可供从事相关专业的工程技术人员参考使用。

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前言

电子信息工程是国内外飞速发展的工程领域之一。为了应对国际化竞争,大学生必须在学习阶段打下坚实的专业基础,发展全面的职业技能。“熟练运用专业英语、有效进行科技交流”是电子信息工程专业大学生的重要专业素养和必备职业技能。

为了提高学生的专业英语阅读写作能力、拓展学生对电子信息工程关键技术的认识、培养具备国际竞争力的技术人才,《电子信息工程专业英语教程(第5版)》[*Technical English Course for Electronic Information Engineering (Fifth Edition)*]充分吸收最新科技成果和英语教学成果,按照先进实用的选材原则和简明系统的组织原则,为电子信息工程专业大学生构建了一个提高英语水平和专业素养的平台。

本教程分为10个主题单元,涵盖了电子信息工程领域的主要技术分支。每个单元由3篇课文、3篇阅读材料和一套单元练习组成。课文侧重展示基础理论和核心技术;阅读材料着力介绍历史沿革、实用技术和未来前景;单元练习采用完形填空、英汉互译、摘要写作的方式训练语言技能。

本教程各单元包含的具体技术内容如下:

1	电子器件	VLSI 技术、微处理器、存储器、数字时代、闪存、微控器
2	电子电路	运算放大器、低通滤波器、ADC、开关电容滤波器、DAC
3	电子系统组件	开关电源、时钟信号源、互连部件、PCB 技术、电源芯片、晶振
4	电子系统	移动电话系统、PC 系统、RFID 系统、GPS 系统、无线局域网
5	现代数字设计	FPGA、VHDL 语言、PLD 发展史、Verilog 语言、SoC
6	数字信号处理	DSP 基础、DSP 处理器、ASP 与 DSP、软件无线电、医学图像处理
7	语音和音频	高保真音频(CD)、音频压缩(MP3)、3G/4G/5G、声码器
8	图像和视频	数字图像、数码相机、电视信号、JPEG 标准、视频编码系统、视频格式
9	嵌入式应用	内核、设计语言、RTOS、ARM 处理器、嵌入式 OS
10	电子仪器与测量	信号源、示波器、逻辑分析仪、信号完整性、虚拟仪器

第1~4单元按照“器件”(device)→“电路”(circuit)→“系统”(system)的思路,全景展示了一个典型电子信息系统的构建过程。关于“器件”,我们选择了当今广泛应用的两种 VLSI 芯片——微处理器和存储器,它们是数字时代电子系统的核心。关于“电路”,我们选择了模拟电路的代表——运算放大器和滤波器,以及混合电路的代表——ADC 和 DAC,它们是数字时代电子系统的外围。众多功能电路可以构成“系统组件”(system component),我们选择了任何电子系统都离不开的“电源设备”(power supply)、“时钟信号源”(clock source)和“互连部件”(interconnects),它们分别相当于系统的“血液”“心脏”和“筋骨”。关于“系统”,我们选择了移动电话、个人计算机(PC)和全球定位系统(GPS)等。

第5~6单元聚焦两种数字电子系统核心的设计手段。一方面,可以利用 VHDL、Verilog 等硬件设计语言,在可编程的 FPGA 和 CPLD 芯片上,设计定制的数字电子系统核心。另一方面,可以利用汇编语言、C 语言等软件设计语言,在可编程的 DSP 芯片上,设计功能强大的信号处理核心。在工程实际中,这两种方式往往配合使用。

第7~8单元通过介绍 CD、MP3 等具体应用,展示了电子信息工程在音频、视频、图像等多媒体领域的发展成果,同时反映出多姿多彩的设计思路和理论成就。学习本单元,有助于激发学生的创新性思维。

第9~10单元面向工程实际,展示了嵌入式产品形成过程的主要方面——选择芯片、选择设计语言、选择操作系统,利用仪器进行测试、验证、故障排除等。关于“芯片”,我们选择了嵌入式领域广泛使用的 ARM。关于“语言”,我们介绍了汇编语言、C 语言、C++ 语言、Java 语言。关于“操作系统”,我们展示了“实时操作系统”(RTOS)和“嵌入式操作系统”(embedded OS)。关于“仪器测量”,我们选择了3件必备仪器——信号源、示波器、逻辑分析仪,并涉及了“信号完整性”(SI)问题和“虚拟仪器”(VI)应用。

在英语语言技能训练方面,本教程采用了3种方式——完形填空、英汉互译、摘要写作。进行“完形填空”练习,有助于雕琢语言细节——语法、词汇、固定搭配、专业术语、专业表达方法等。进行“英汉互译”练习,有助于明辨英汉语言差异、文化差异和思维方式差异,从而提高专业阅读、学术写作和科技交流的水平。进行“摘要写作”练习,有助于熟悉科技文体格式、用词特点和写作技巧,为将来写作科技论文打下良好基础。

任何语言能力的培养,必须在真实的场景中训练才会收到实效。在本教程中,各单元练习全部取材于国外大学教材、科技专著、国际会议论文、工程技术文档(芯片使用指南、用户手册、技术白皮书)、业内专家文章和著名公司网站等(详见参考资料),以期达到“利用英语学专业、通过专业练英语”的教学目标。

为了便于学生自学,本教程提供了课文参考译文、练习参考答案。此外,本教程在附录中还提供了“科技英语语音手册”和“科技英语词汇手册”。

为了便于教师授课及丰富课堂内容,本教程配有 PowerPoint 电子讲稿、阅读材料参考译文、模拟试卷及答案、视频材料及脚本等教辅资料。凡使用本教程作为教材的教师,均可登录电子工业出版社华信教育资源网(www.hxedu.com.cn)注册下载,或者电话联系 010-88254531 免费获得。

为方便读者学习,相关视频、试卷及生词短语/专业术语速查表等以二维码的形式给出,扫描下方二维码即可打开。



本教程自 2004 年 7 月出版第 1 版以来,受到了高校师生和工程技术人员的普遍认可和欢迎。这次修订是在前 4 版的基础上,充分采纳了每位读者的合理化建议,全面更新了技术内容和语言内容。希望最新版教程更加贴近教学、科研和工程实际。

由于作者水平所限,书中难免有纰漏和欠妥之处。本教程的读者反馈邮箱为 rzgwriting@163.com,欢迎各位读者不吝赐教!

编著者

使用说明

学生自学建议

正式学习前,建议通读附录。对于没有系统学习过科技英语课程的学生,最好在学习本教程之前,将附录中的“科技英语语音手册”和“科技英语词汇手册”通读一遍。

全面理解核心学术词汇,准确记忆关键科技术语。面对海量英语词汇,必须要有选择。那些出现频率高、词义繁多、用法灵活的词汇是突破的重点。在专业英语学习中,有两类重点词汇——“核心学术词汇”(Core Academic Words)和“关键科技术语”(Key Technical Terms)。请分别参照课文词汇表的 New Words & Expressions 部分和 Technical Terms 部分。

泛读课文内容,聚焦英文表达技巧。在对照参考译文阅读课文的时候,不要仅限于明白大概意思就行了,要把主要精力集中于“这个中文意思,英文是怎么表达的”。在很多情况下,英文中有若干种表达方法。通过做笔记、摘抄和总结的办法,就可以不断地积累各种常用的英文表达技巧。

翻译阅读材料,训练技术信息提取能力。作为将来的工程师,显然要具备从英文技术资料中提取关键信息的能力。本教程中的阅读材料包含了丰富的技术题材。如果对于某方面内容特别感兴趣,那么就可以尝试着翻译一下。这也是深入学习词汇、语法和文化的最好方式。

利用单元练习,进行自我测试。本教程中的单元练习,全部来自真实的技术资料,有利于学生测试自己真实的专业英语水平。

教师授课建议

根据教学实际情况,恰当选择精讲课文及段落。本教程的课文难度分为高、中、低三档,适用于各类型大学、各种水平学生的专业英语教学。课文的选材,既有高难度的科技专著、学术论文、技术手册,也有中等难度的大学教材、用户手册、技术白皮书,还有比较易懂的综述文章、科普读物。根据实际情况,教师要选择适合课堂教学的内容,作为精讲课文和精讲段落。其他课文和段落,可以安排学生课前预习或课后自学,也可以根本不去涉及。

利用英语学专业,通过专业练英语。专业英语课程实践性很强。在课堂上,教师不但要精讲,更要精练。一段精讲课文,既可以训练学生从中快速、准确提取技术信息的阅读能力,也可以训练学生撰写摘要、模仿造句、独立作文的能力。这种“阅读”→“分析”→“写作”的教学模式,被证明是非常成功的。

适时适量引入音频、视频,丰富课堂内容,激发学习兴趣。为了提高专业英语听说能力,可以在课堂教学中引入一定量的音、视频材料,并设法引导学生学会利用网络进行专业英语的听说读写交流。

强调科技英语阅读写作,提高科技交流职业技能。作为将来的工程师,阅读能力和写作能

力最为重要。在科技交流中,无论查询资料、进行设计,还是联系业务,都离不开阅读和写作。有效的科技交流,要求“准确”“快速”,而这种能力不经过专业训练是无法达到的。

扩展阅读建议

科技交流

- [1] W.S.法依弗, K.E. 阿德金斯. 大学科技英语国际交流教程. 任治刚, 译. 北京: 电子工业出版社, 2015.
- [2] Charles W. Knisely, Karin I. Knisely. Engineering Communication. Cengage Learning, 2014.
- [3] Michael Alle. The Craft of Scientific Presentations: Critical Steps to Succeed and Critical Errors to Avoid (2nd Edition). Springer, 2013.

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- [1] John M. Swales, Christine Feak. Academic Writing for Graduate Students (3rd Edition). ELT, 2012.
- [2] R.A.戴, B.盖斯特尔. 科技论文写作与发表教程(第8版). 任治刚, 译. 北京: 电子工业出版社, 2018.

词汇语法

- [1] Alison Pohl, Nick Brieger. Technical English: Vocabulary and Grammar. Summer-town Publishing, 2002.
- [2] Robert A. Day, Nancy Sakaduski. Scientific English: A Guide for Scientists and Other Professionals (3rd Edition). Greenwood, 2011.
- [3] Nigel A. Caplan. Grammar Choices for Graduate and Professional Writers. University of Michigan Press/ELT, 2012.

教材选用建议

对于同时开设“电子信息工程专业英语”“通信工程专业英语”的学校,还可以选用《电子通信专业英语简明教程》(任治刚主编,电子工业出版社,2015)。该教程篇幅适中、内容简明,并专门设立“科技英语、学术写作和职场交流”部分。该教程也适合有志留学或深造的学生自修及国际化IT企业人士阅读。

对于“通信工程专业英语”感兴趣的读者,可以参照《通信工程专业英语教程》(任治刚主编,电子工业出版社,2016)。该教程题材广泛、内容实用、练习丰富,并提供“学术英语提要”“科技论文写作”等内容,可以满足读者在就业、深造或留学时的切实需求。

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Unit 1

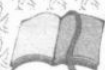
Electronic Devices



Lesson 1 VLSI Technology



Lesson 2 Memory Devices



Lesson 3 Microprocessors



Passage 1 The Digital Age



Passage 2 Flash Memory



Passage 3 Microcontrollers

惠州学院内部使用

Lesson 1 VLSI Technology

One of the key inventions in the history of electronics^[1], and in fact one of the most important inventions over period^[2], was the transistor. It was invented by Bell Laboratories^[3] in 1947. In short, a transistor is a device that conducts a variable amount of electricity through it, depending on how much electricity is input to it. In other words, it is a digital switch. However, unlike the vacuum tube, it is solid state. This means that it doesn't change its physical form as it switches. There are no moving parts in a transistor.

The advantages of the transistor over the vacuum tube^[4] were enormous. Compared to the old technology, transistors were much smaller, faster, and cheaper to manufacture. They were also far more reliable and used much less power. The transistor is what started the evolution of the modern computer industry in motion.^[5]

The transistor was originally a single, discrete device, which you could place individually into a circuit much like any other. Today, some special-purpose transistors are still used that way. What allowed the creation of modern processors was the invention of the integrated circuit^[6], which is a group of transistors manufactured from a single piece of material and connected together internally, without extra wiring. Integrated circuits are also called ICs or chips.

A special material is used to make these integrated circuits. While most materials either insulate from electrical flow (air, glass, wood) or conduct electricity readily (metals, water), there are some that only conduct electricity a small amount, or only under certain conditions. These are called semiconductors. The most commonly used semiconductor is of course silicon.

By careful chemical composition and arrangement, it is possible to create a very small transistor directly on a layer of silicon, using various technologies to manipulate the material into the correct form. These transistors are small, fast and reliable, and use relatively little power. The first integrated circuit was invented in 1958 by Texas Instruments.^[7] It contained just six transistors on a single semiconductor surface.

After the invention of the integrated circuit, it took very little time to realize the tremendous benefits of miniaturizing and integrating larger numbers of transistors into the same integrated circuit. More transistors (switches) were required in order to implement more complicated functions. Miniaturization was the key to integrating together large numbers of transistors while increasing hardware speed and keeping power consumption and space requirements manageable.

Large-scale integration (LSI) came to refer to the creation of integrated circuits that had previously been made from multiple discrete components. These devices typically contained

hundreds of transistors. Early computers were made from many of these smaller ICs connected together on circuit boards.

As time progressed after the invention of LSI integrated circuits, the technology improved and chips became smaller, faster and cheaper. Building on the success of earlier integration efforts, engineers learned to pack more and more logic into a single circuit. This effort became known as very large-scale integration (VLSI). VLSI circuits can contain millions of transistors.

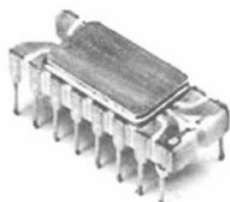


Figure 1.1 Intel 4004

Originally, the functions performed by a processor were implemented using several different logic chips. Intel^[8] was the first company to incorporate all of these logic components into a single chip. This was the first microprocessor, the 4004 (see Figure 1.1), introduced by Intel in 1971. All of today's processors are (highly advanced!) descendants of this original^[9] 4-bit CPU.

New Words & Expressions

invention [ɪn'venʃən] *n.* 发明

device [dɪ'vaɪs] *n.* 器件

conduct [kən'dʌkt] *vt.* 传导

variable ['veəriəbl] *adj.* 可变的

amount [ə'maʊnt] *n.* 数量

vacuum ['vækjuəm] *n.* 真空

solid ['sɒlɪd] *adj.* 固体的

advantage [əd'vɑ:ntɪdʒ] *n.* 优势

enormous [ɪ'nɔ:məs] *adj.* 巨大的

manufacture [ˌmænjʊ'fæktʃə] *vt.* 批量生产

reliable [rɪ'laɪəbl] *adj.* 可靠的

evolution [ˌevə'lu:ʃən] *n.* 发展; 演变

originally [ə'rɪdʒənəli] *adv.* 起初

individually [ˌɪndɪ'vɪdʒuəli] *adv.* 分别地

internally [ɪn'tɜ:nəli] *adv.* 内部地

composition [ˌkɒmpə'zɪʃən] *n.* 合成

arrangement [ə'reɪndʒmənt] *n.* 排列

directly [daɪ'rektli] *adv.* 直接地

layer ['leɪə] *n.* 层

various ['veəriəs] *adj.* 多种不同的

manipulate [mə'nɪpjuleɪt] *vt.* 处理

contain [kən'teɪn] *vt.* 包含

surface ['sɜ:fɪs] *n.* 表面

tremendous [trə'mendəs] *adj.* 巨大的

benefit ['benɪfɪt] *n.* 益处

miniaturize ['mɪniətʃəraɪz] *vt.* 使微型化

integrate ['ɪntɪɡreɪt] *vt.* 集成

consumption [kən'sʌmpʃən] *n.* 消耗

requirement [rɪ'kwəɪəmənt] *n.* 需求

manageable ['mænɪdʒəbəl] *adj.* 可处理的

refer to ... 是指……

previously ['pri:vɪəsli] *adv.* 此前

multiple ['mʌltɪpl] *adj.* 多个的

progress [prə'ɡres] *n.* 进步

implement ['ɪmplɪmənt] *vt.* 实现

incorporate [ɪn'kɔ:pəreɪt] *vt.* 合并

introduce [ɪn'trə'dju:s] *vt.* 推出

advanced [əd'vænst] *adj.* 先进的

descendant [dɪ'sendənt] *n.* 后代

original [ə'rɪdʒənəl] *adj.* 最初的

Technical Terms

electronics [ˌɪlekˈtrɒnɪks] *n.* 电子学
transistor [trænˈsɪstə] *n.* 晶体管
electricity [ˌɪlekˈtrɪsəti] *n.* 电
digital [ˈdɪdʒɪtəl] *adj.* 数字的
switch [swɪtʃ] *n.* 开关
power [ˈpaʊə] *n.* 功率
discrete [dɪsˈkri:t] *adj.* 分立的
circuit [ˈsɜ:kɪt] *n.* 电路
chip [tʃɪp] *n.* 芯片
insulate [ˈɪnsjuleɪt] *vt.* 绝缘
semiconductor [ˌsemɪkənˈdʌktə] *n.* 半导体
silicon [ˈsɪlɪkən] *n.* 硅
miniaturization [ˈmɪnɪətʃəraɪˈzeɪʃən] *n.* 缩微化
component [kəmˈpəʊnənt] *n.* 元器件;组件;部件
logic [ˈlɒdʒɪk] *n.* 逻辑
microprocessor [maɪkrəʊˈprəʊsesə] *n.* 微处理器
solid state 固态
power consumption 功耗
circuit board 电路板
IC *abbr.* integrated circuit 集成电路
LSI *abbr.* large-scale integration 大规模集成
VLSI *abbr.* very large-scale integration 超大规模集成
CPU *abbr.* central processing unit 中央处理器

Notes

1. electronics 可译作“电子学”“电子技术”或“电子线路”“电子设备”。例如,“镉是电子工业有毒废物”(Cadmium is a toxic waste product of *electronics* industry)。后缀 -cs 表示“学术”,如“美学”(aesthetics)、“伦理学”(ethics)、“经济学”(economics)。
2. period 可指“一段时间”,如“在四天之内”(over a *period* of four days)“此项研究为期六个月”(The study will be carried out over a six-month *period*)。介词 over 可表示时间或空间的跨越,如“此图展示了过去 20 年来 Y 随 X 变化的情况”(This figure shows how Y varied in relationship with X *over* the last 20 years)。
3. Bell Laboratories(又称 Bell Labs)是贝尔实验室(www.bell-labs.com),总部位于美国新泽西州的默里山(Murray Hill, New Jersey)。1947 年 12 月 23 日,该实验室的 Bill Shockley、Walter Brattain 和 John Bardee 发明了晶体管。

4. The advantages of Y over X 结构表示“Y 相对于 X 的优势”。advantage 常见搭配有 a big/great/major advantage、the main advantage、have an advantage 和 the advantage of sth.。
5. 此句为强调结构,使用 what 表语从句强调主语(the transistor)。
6. 此句为强调结构,使用 what 主语从句强调表语(the invention of the integrated circuit)。
7. Texas Instruments 是指德州仪器公司(www.ti.com),总部位于美国得克萨斯州的达拉斯(Dallas, Texas)。1958 年,该公司的 Jack Kilby 发明了第一片集成电路。
8. Intel 是指英特尔公司(www.intel.com),其总部位于美国加利福尼亚州的圣克拉拉(Santa Clara, California)。1968 年,Robert Noyce 和 Gordon Moore 创建英特尔公司。
9. original 源自 origin(起点),意为“最初的”,如“原计划”(original plan)、“原始特征”(original features)、“将讨论返回到开始的话题”(steer the discussion to the original topic)。

Lesson 2 Memory Devices

Memories can be made in mechanical, magnetic, optical, biological and electronic technologies. Examples of magnetic memories are tapes, floppy disks, hard drives and ferroelectric^[1] RAMs. Examples of optical memories are CD-ROMs, rewritable CDs. Electronic memory is used extensively in computer equipment since it is the fastest available. All electronic memory today can be in separate IC format, module format, or can be part of an IC as a macro-function or cell. Table 1.1 is an overview of some electronic memories.

Table 1.1 Overview of Common Electronic Memory Devices

Type	Properties	Writable	Non-volatile	Speed	Cost
Flip-flop	One-bit register.	Yes	No	Ultra fast	Very high
	Used as basic building blocks in digital circuits.				
Register	Set of flip-flops holding a byte, word or long word.	Yes	No	Ultra fast	Very high
	Used in complex chips such as CPUs.				
SRAM	Array of flip-flops that is addressable.	Yes	No	Very fast	High
	Used for temporary storage of data or cache ^[2] .				
DRAM	Array of storage cells which is addressable.	Yes	No	Fast	Moderate
	Used for main computing data storage.				
ROM	Array of hard-wired cells that is addressable.	No	Yes	Very fast	Low
	Programming done at time of chip manufacture.				
EEPROM	Electrically erasable programmable ROM.	Yes	Yes	Low	High
	Number of write cycles is limited.				

Flip-flop

A flip-flop is basically a bi-state circuit in which either a 0 or 1 state can reside. Because of its simplicity, the flip-flop is extremely fast. As a basic element, the flip-flop is used in

digital circuits and ICs. A flip-flop will lose its state when the supply voltage is removed. Therefore, it is volatile.

Register

A register is a set of flip-flops in parallel. Typically a register is 8, 16, 32 or 64 bits wide. Often a register is used to hold data, address pointers, etc. A register is volatile and very fast just like the flip-flop.

SRAM (static random access memory)

An SRAM is an array of addressable flip-flops. The array can be configured as such that the data comes out in 1-bit, 4-bit, 8-bit, and etc. SRAM is simple, fast and volatile just like the flip-flop, its basic memory cell. SRAM can be found on microcontroller boards (either on or off the CPU chip), where the amount of memory required is small and it will not pay off to build the extra interface circuitry for DRAMs. In addition, SRAM is often used as cache because of its high speed.

SRAM comes in many speed classes, ranging from several ns for cache applications to 200ns for low power applications. SRAM exists in both bipolar and MOS technology. CMOS^[3] technology boasts the highest density and the lowest power consumption. Fast cache memory can be constructed in BiCMOS technology, a hybrid technology that uses bipolar transistors for extra drive. The fastest SRAM memories are available in emitter coupled logic (ECL) bipolar technology. Because of the high power consumption, the memory size is limited in this technology.

A special case of SRAM memory is content addressable memory (CAM)^[4]. In this technology, the memory consists of an array of flip-flops, in which each row is connected to a data comparator. The memory is addressed by presenting^[5] data to it (not an address!). All comparators will then check simultaneously^[6] if their corresponding RAM register holds the same data. The CAM will respond with the address of the row (register) corresponding to the original data. The main application for this technology is fast lookup tables. These are often used in network routers.

DRAM (dynamic random access memory)

The word “dynamic” indicates that the data is not held in a flip-flop but rather in a storage cell. The data in a storage cell must be refreshed (read out and re-written) regularly because of leakage. The refresh time interval is usually 4 to 64 ms. The storage cell only requires one capacitor and one transistor, whereas^[7] a flip-flop connected in an array requires 6 transistors. In trench capacitor memory technology, which is used in all modern DRAMs, the transistor is constructed above the capacitor so that the space on chip is ultimately minimized. For this reason, DRAM technology has a lower cost per bit than SRAM technology. The disadvantage of the extra circuitry required for refreshing is easily offset by the lower price per bit when using large memory sizes.

DRAM memory is, just like SRAM memory constructed as an array of memory cells. A major difference between SRAM and DRAM, however, lies in the addressing technique. With an SRAM, an address needs to be presented and the chip will respond with presenting the data of the memory cell at the output, or accepting the data at the input and write it into the addressed cell. With DRAM technology, this simple approach is impossible since addressing a row of data without rewriting it will destruct all data in the row because of the dynamic nature.

ROM (read only memory)

ROMs are also called mask^[8]-ROMs or mask programmed ROMs. This is because a ROM needs to be programmed by setting its cells to either 0 or 1 at the time of manufacture. Usually the 0 or 1 is formed by the presence or absence of an aluminum line. This aluminum pattern is defined by a lithographic mask used in one of the last steps of manufacture. Therefore these devices are often called mask-ROMs.

The advantage of ROM is that it can be manufactured at the lowest price in high volumes. Another advantage in some applications is that it is impossible to alter the data once the chips are made, and that no further programming and testing are required. On the other hand, if the data or code must be changed this can be a small disaster. The rest of the chips will end in the dustbin and new chips will have to be made.

EEPROM (electrically erasable programmable ROM)

This means that the chip can be programmed like an EPROM, but can be erased electrically. As a result, no UV source is required. EEPROMs can be erased on a byte-by-byte basis.

New Words & Expressions

mechanical [mɪ'kæni:kəl] *adj.* 机械的

extensively [ɪk'stensɪvli] *adv.* 大量地; 广泛地

available [ə'veɪləbl̩] *adj.* 可获得的; 可用的

format ['fɔ:mæt] *n.* 格式

module ['mɒdʒul] *n.* 模块; 功能块

property ['prɒpəti] *n.* 特性

volatile ['vɒlətaɪl] *adj.* 易失的

array [ə'reɪ] *n.* 阵列

temporary ['tempərəri] *adj.* 临时的

moderate ['mɒdərət] *adj.* 中等的

simplicity [sɪm'plɪsəti] *n.* 简易性

parallel ['pærəlel] *adj.* 并行的

static ['stætɪk] *adj.* 静态的

simultaneously [saɪmə'lteɪniəsli] *adv.* 同时地

corresponding [ɪkɒrɪ'spɒndɪŋ] *adj.* 相应的

respond [rɪ'spɒnd] *vi.* 响应

original [ə'rɪdʒənəl] *adj.* 最初的

dynamic [daɪ'næmɪk] *adj.* 动态的

indicate ['ɪndɪkeɪt] *vt.* 标明

regularly ['regjələli] *adv.* 定期地

whereas [weə'æz] *conj.* 然而

ultimately [ʌl'tɪmətli] *adv.* 最终

minimize ['mɪnɪmaɪz] *vt.* 减至最低

disadvantage [ɪdɪsəd'ventɪdʒ] *n.* 缺点; 劣势

offset ['ɒfɪset] *vt.* 抵消; 弥补

major ['meɪdʒə] *adj.* 主要的; 重要的